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# **Micro and Nano-Manufacturing**

Guest Editor:

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Deadline for manuscript submissions:

closed (30 November 2018)

## Message from the Guest Editor

Dear Colleagues,

Micro- and nano-scale manufacturing is gaining more attention due to production miniaturization and customization. High precision and product quality are difficult to achieve at this length scale; thus, a deeper understanding of the processes, development of characterization methods, modeling and simulations, and monitoring are required for the improvement of product quality and mass scale productivity. This Special Issue of *JMMP* will focus on advances in micro- and nano-scale manufacturing processes and systems that address the aforementioned requirements. Both theoretical and experimental contributions are welcome. Application-oriented novel manufacturing processes and systems are also of interest.

Dr. Martin Byung-Guk Jun Guest Editor











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## **Message from the Editor-in-Chief**

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